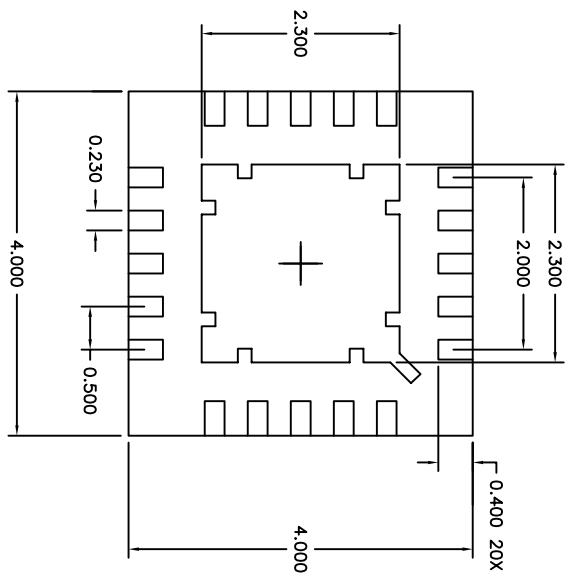
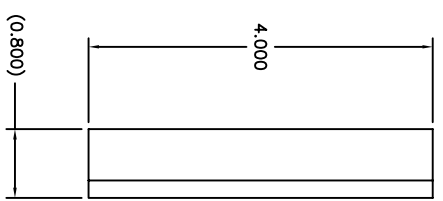
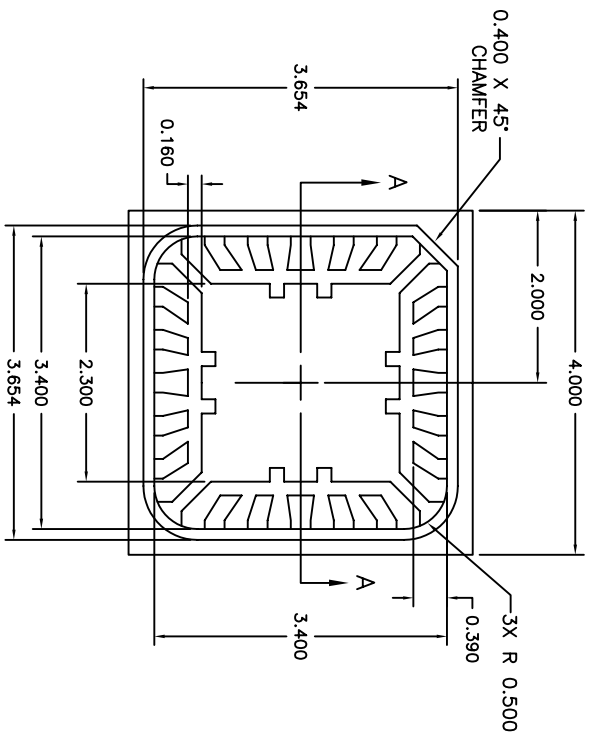


2

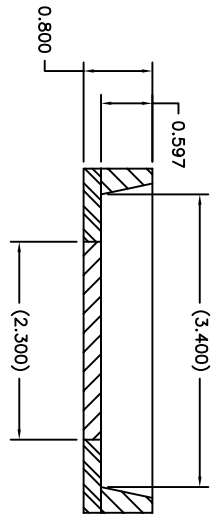
1

REVISIONS			APPROVED
ECON NO.	DATE	DESCRIPTION	D.BENANDINO
10607	2/26/06	PRODUCTION RELEASE	



TOP VIEW

BOTTOM VIEW



SECTION A-A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
  2. LEAD FRAME: COPPER, 194 FH.
  3. LEAD FINISH: FULL GOLD PLATE.
  4. LEAD THICKNESS: 0.2030 ± 0.0076.
  5. FRAME THICKNESS: 0.2030 ± 0.0076.
  6. DIE PAD: 2.300mm X 2.300mm.
  7. JEDEC OUTLINE: MO-220 (VGGD-5)



THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: XXX ± 0.015 ANGLES: ± 1° DO NOT SCALE DRAWING

DRAWN BY	W. GRIFFITTS	DATE	2/26/06
APP BY	P. FLASKERUD	DATE	2/26/06
CUSTOMER	---		

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**SEMPAC, INC.**  
 Open-Pak™ Technologies  
 www.sempac.com  
 588 E. WEDDELL DRIVE, SUITE 5  
 SUNNYVALE, CALIFORNIA 94089  
 PHONE: (408) 400-9002 FAX: (408) 400-9006

SIZE	PART NO.	REV
A	MLP4X4-20-OP-01	1
SCALE	NONE	
CAD FILE	MLP4X4-20-OP-01-R1.DWG	
SHEET	1 OF 1	

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